

Appl. No.: 10/706,862
Amendment Dated April 6, 2005
Reply to Office Action of November 22, 2004

Amendments to the Specification:

On page 7, please replace the second paragraph beginning on line 7 as follows:

On the other hand, the following methods are in the 2001-110529th according to the Japanese Patent Provisional Publication Nos. ~~2001-110529~~ 2001-115029 and 2001-203197, a coating liquid is obtained by hydrolysis and condensation of a silane compound and provides excellent dielectric properties. Because a modulus of elasticity required in the manufacturing process of an actual semiconductor is 5 GPa or higher, however, the mechanical strength is not sufficient in these inventions.